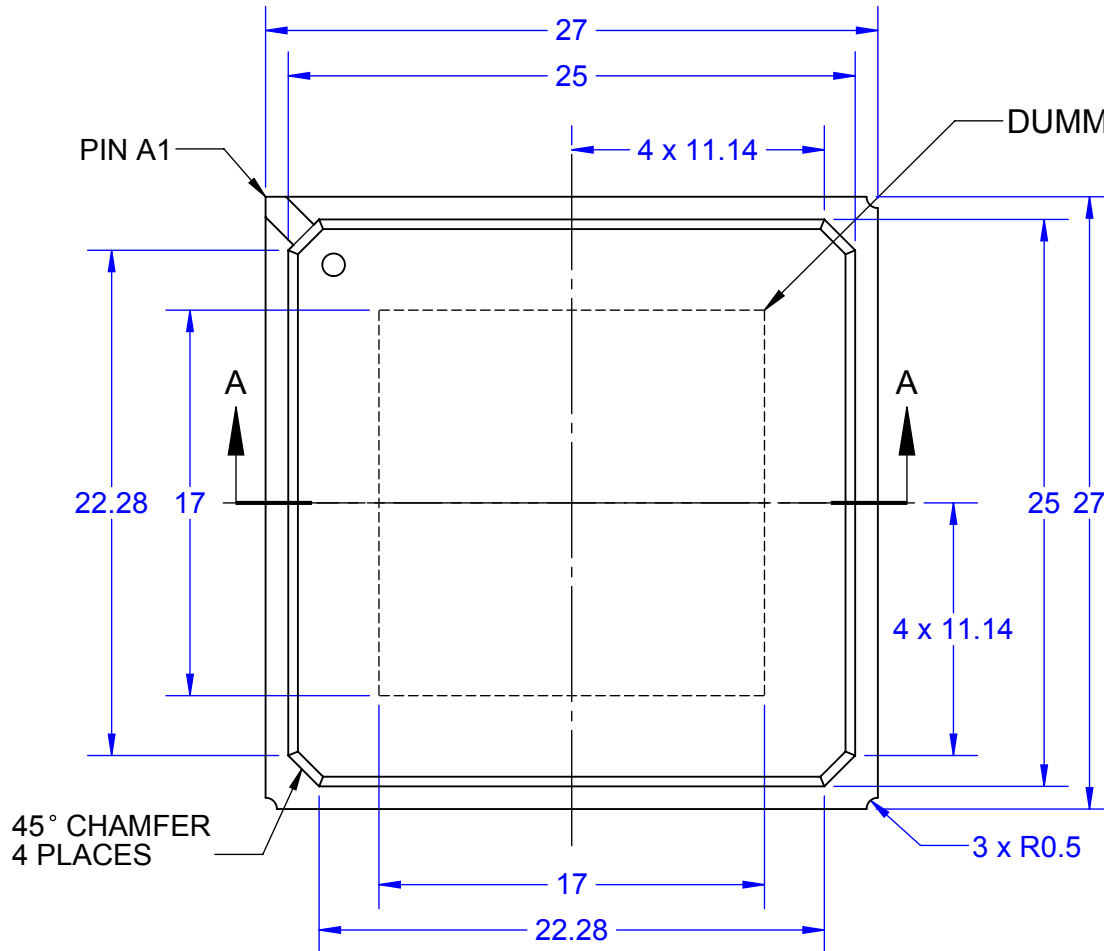
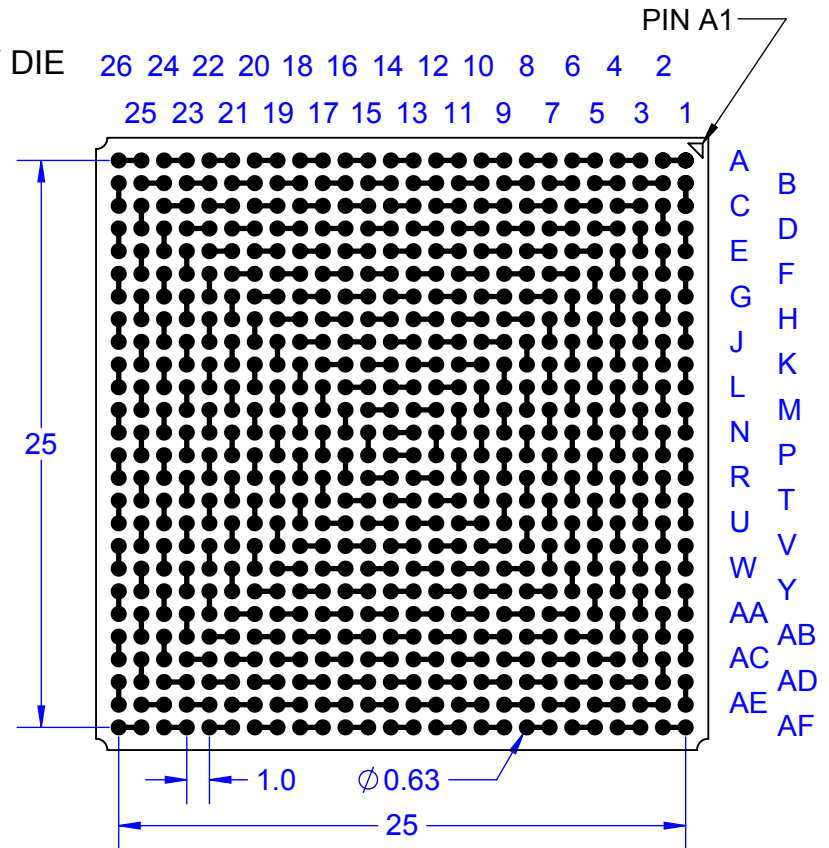


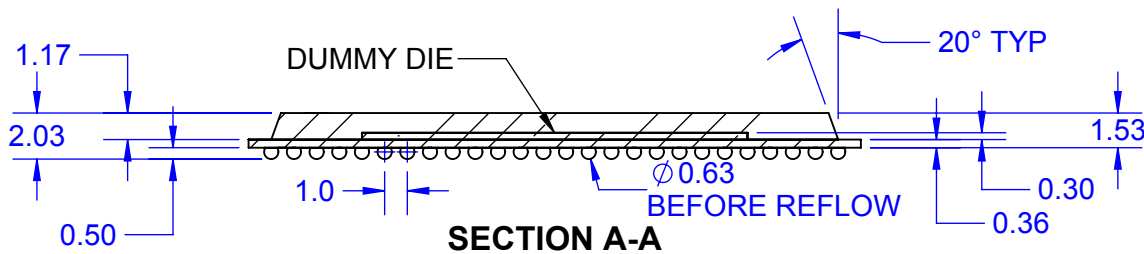
TOP VIEW



BALL VIEW



- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.63mm (25 MIL).
 - 4) SOLDER MASK DEFINED PAD OPENING: 0.45mm (17.7 MIL).
 - 5) PAD Cu DIAMETER: 0.60mm (23.6 MIL).
 - 6) SUBSTRATE MATERIAL: BT.
 - 7) DUMMY DIE IS OPTIONAL.
 - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
 - 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

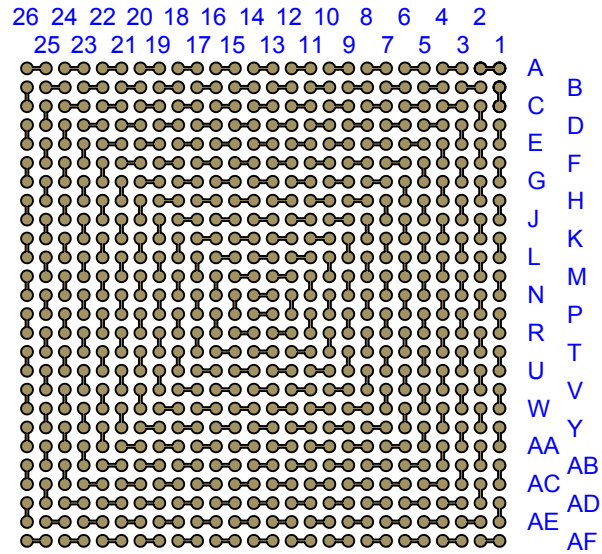


SECTION A-A

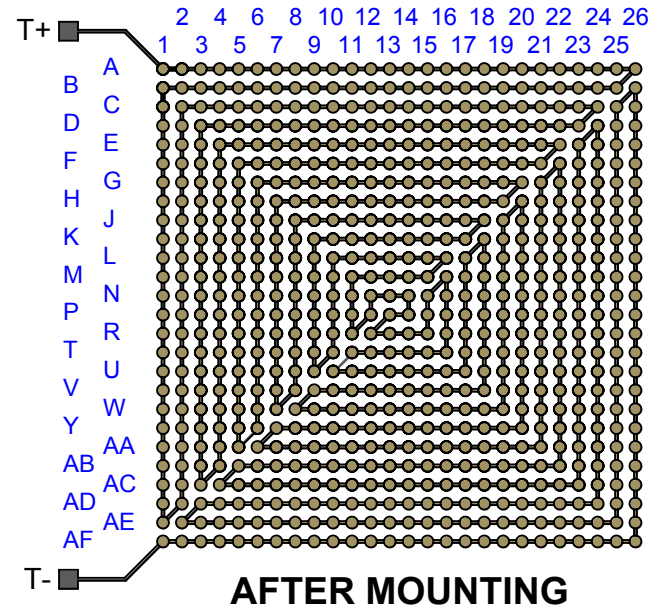
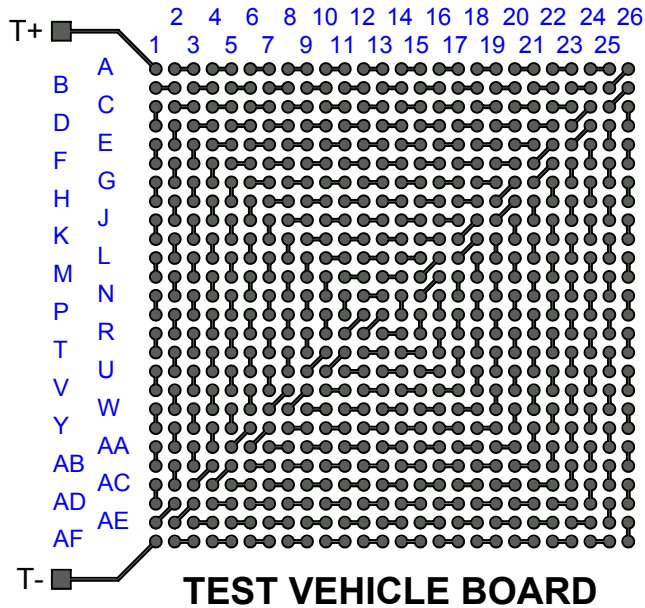
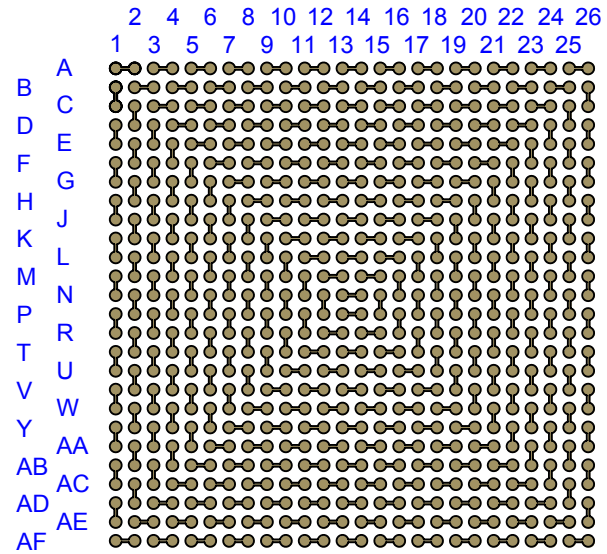
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-Free	RoHS	Si DIE
BGA676T1.0C-DC269BD	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA676T1.0-DC269BD	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE				
DRAWN T.Au	05/21/15				
ENG M. Hart	05/21/15	TITLE	BGA676T1.0-DC269BD DAISY CHAIN DUMMY		
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		3:1	A	512694	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER: 0.60mm (23.6 MIL).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH: 0.15mm (6 MIL).
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.45mm (17.7 MIL).

TopLine®			
TITLE		BGA676T1.0-DC269BD DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
2.5:1	A	512694	A
DO NOT SCALE DRAWING			SHEET 2 OF 2